# Spectra<sup>™</sup> FOUPs

Front opening unified pod platform with superior microenvironment control

The Spectra™ FOUP holds 300 mm wafers safely and securely while they are transported and transferred within the fab through hundreds of sophisticated process steps. Designed not only to address particles but to also minimize and control VOC, oxygen, and relative humidity (RH), our FOUPs provide superior microenvironment control, optimal automation integration, and low cost of ownership.

Hydrophobic materials of construction with clean carbon loading are designed for low moisture and low volatile absorption and desorption. Generous radii in part design and open wash slots in the FOUP door cover eliminate water or moisture traps, enabling effective cleaning and reducing drying cycle times.

Our Spectra FOUP meets all applicable SEMI<sup>®</sup> standards. The industry-proven door is designed for equipment interoperability and long life. Wafer supports are integral with the shell to give excellent wafer plane performance and reliable wafer access. The top robotic flange and bottom kenematic coupling ensure accurate equipment interfaces.

These advanced FOUPs create a sealed wafer environment that provides static protection, white-light shielding, and a considerable positive impact on device yield.

#### **APPLICATIONS**

- FOUP platform that provides clean and secure 300 mm transport and handling
- Automation compatibility provides low cost of ownerhip



Advanced inert gas diffusion purge further protects wafers

#### **FEATURES & BENEFITS**

Industry-proven door design	Provides equipment interoperability and long life	
Generous radii in part design and open wash slots in the FOUP door cover	Eliminate water or moisture traps, enabling effective cleaning and reducing drying cycle times	
Integral wafer supports	Give excellent wafer plane performance and reliable wafer access	
ESD shell option	Provides added wafer protection	
Optimized hydrophobic materials of construction	Provide wafer contact and microenvironment control	
Sealed wafer environment	Provides static protection, white-light shielding, and offers a considerable positive impact on device yield	



#### **SPECIFICATIONS**

Dimensions	Width	416 mm (16.4")
	Depth	333 mm (13.1")
	Height	335 mm (13.2")
Weight	Empty	4.2 kg (9.26 lb)
	With wafers	7.3 kg (16.09 lb)
Wafer spacing	10 mm (0.39")	
Capacity	26 wafers	

#### **Materials Of Construction**

- Ultrapure polycarbonate or barrier material used in the FOUP shell, door housing, and door panels
- Carbon-filled PEEK or high-temperature barrier material (XT EBM) used in wafer contact areas in the shell, door housing, and door components
- Thermoplastic elastomer material used in the critical door seal
- Entegris moisture barrier material (EBM) available to enable leading-edge wafer processing technology

#### **Configuration Options And Accessories**

#### **Shell and Door Color Options**

• Amber, red, green, clear, and black (ESD shell only)

#### **Purge Options**

- Front/rear standard purge
- Rear advanced diffuser

# **Segregation Options**

• Info pads configurable by customer

## **Identification Options**

- Bar code and alphanumeric character labels
- Color handle inserts
- Cardholders
- RFID tags with read/write capability

#### FOR MORE INFORMATION

Please call your Regional Customer Service Center today to learn what Entegris can do for you. Visit entegris.com and select the Contact Us link to find the customer service center nearest you.

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